

IN THE SPECIFICATION

On page 3, line 20, please delete "side elevation" and insert ~~--~~partial cross-sectional--.
On page 3, line 21, please delete "side elevation" and insert ~~--~~partial cross-sectional--.
On page 3, line 23, please delete "side elevation" and insert ~~--~~cross-sectional--.
On page 3, line 24, please delete "side elevation" and insert ~~--~~cross-sectional--.
On page 3, line 25, please delete "side elevation" and insert ~~--~~partial cross-sectional--.
On page 8, line 5, please delete "416" and insert --417--.
On page 8, line 18, please delete "412" and insert --414--.

IN THE CLAIMS

Please amend claims 1, 9, 11, 12, 18, 20, 21 and 22, as follows:

Sub B1
a1
1. (Amended) A solderless mounting socket, comprising:
a socket body having a first side and a second, opposite side, the body having a plurality
of vias extending therethrough;
a plurality of solderless conductive terminals within the vias, wherein the terminals
comprise:
an elastically deformable member.

Sub B3
a2
9. (Amended) A method of mounting a socket to a board, the socket having a plurality of
solderless compressible contact terminals, comprising:
applying an adhesive layer to a board side of the socket;
leveling the adhesive layer to make the adhesive layer substantially coplanar with the
solderless compressible contact terminals of the socket; and
adhering the socket to the board compressing the plurality of solderless compressible
contact terminals against complementary electrical contacts on the board.

sub B4
A3

11. (Amended) A method of mounting a package to a board using a socket having solderless compressible contact terminals, the method comprising:
applying a first adhesive layer to a first, package side of the socket;
leveling the first adhesive layer to make the adhesive layer substantially coplanar with the solderless compressible contact terminals;
adhering the package to the first adhesive layer;
applying a second adhesive layer to a second, board side of the socket;
leveling the second adhesive layer to make the second adhesive layer substantially coplanar with the solderless compressible contact terminals; and
adhering the board to the second adhesive layer compressing the solderless compressible contact terminals against complementary electrical contacts on the board.

12. (Amended) A solderless circuit interconnect, comprising:
a circuit board carrier having a plurality of through holes formed therein; and
a plurality of solderless conductive terminals with lands at each end, each terminal in one of the through holes, wherein each conductive terminal comprises an elastically deformable member.

sub B2
A4

18. (Amended) A circuit package, comprising:
a substrate having a plurality of solderless conductive terminals therethrough;
a first adhesive layer affixed to a first side of the substrate; and
a package affixed to the first adhesive layer.

sub B7
A5

20. (Amended) An integrated circuit, comprising:
a substrate having a plurality of vias therein; and
a plurality of elastically deformable solderless terminals, each terminal positioned in a via.

21. (Amended) A circuit assembly, comprising:
a substrate having a built-in socket, the socket having a plurality of vias therein;